



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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200mW, 4 PIN DIP Phototransistor Photocoupler

FEATURES

- Current transfer ratio (CTR: MIN.80% at $I_F=5\text{mA}$, $V_{CE}=5\text{V}$)
- High isolation voltage between input and output ($V_{ISO}=5000\text{V rms}$)
- High collector-emitter voltage ($V_{CEO}:70\text{V}$)
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Programmable controllers
- System appliances, measuring instruments
- Signal transmission between circuits of different potentials and impedances

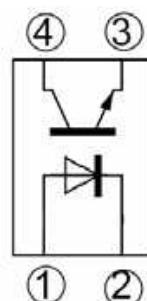
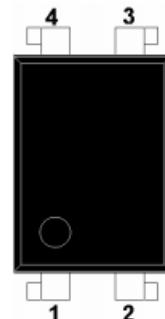
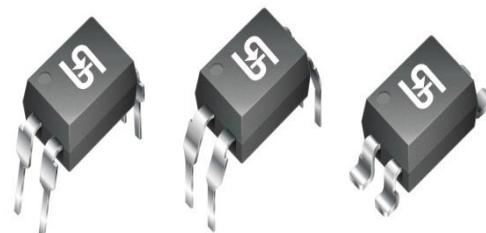
MECHANICAL DATA

- Case: DIP-4 , DIP-4M , SOP-4
- Molding compound: UL flammability classification rating 94V-0
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
CTR	80-600	%
V_{CEO}	70	V
P_{tot}	200	mW
I_C	50	mA
V_{iso}	5000	Vrms
Package	DIP-4 DIP-4M SOP-4	
Configuration	Single Dice	



HALOGEN
FREE



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)				
PARAMETER		SYMBOL	PART NUMBER	UNIT
Input	Forward current	I_F	50	mA
	Peak forward current (Note 1)	I_{FM}	1	A
	Reverse voltage	V_R	6	V
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	V_{CEO}	70	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	50	mA
	Collector power dissipation	P_C	150	mW
Total power dissipation		P_{tot}	200	mW
Isolation voltage (Note 2)		V_{iso}	5000	Vrms
Operating temperature		T_{opr}	-30 to +100	°C
Storage temperature		T_{stg}	-55 to +125	°C
Soldering temperature (Note 3)		T_{sol}	260	°C

Notes:

1. Pulse width $\leq 100\text{ms}$, Duty ratio : 0.001
2. 40 to 60% RH, AC for 1 minute
3. For 10s

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER		CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Input	Forward voltage	$I_F=20\text{mA}$	V_F		1.2	1.4	V
	Peak forward voltage	$I_{FM}=0.5\text{A}$	V_{FM}			3.0	V
	Reverse current	$V_R=4\text{V}$	I_R			10	μA
	Terminal capacitance	$V=0, f=1\text{kHz}$	C_t		30	250	pF
Output	Collector dark current	$V_{CE}=20\text{V}, I_F=0$	I_{CEO}			10^{-7}	A
Transfer Characteristics	Current transfer ration (Note 1)	$I_F=5\text{mA}, V_{CE}=5\text{V}$	CTR	80		600	%
	Collector-emitter saturation voltage	$I_F=20\text{mA}, I_C=1\text{mA}$	$V_{CE(\text{sat})}$		0.1	0.2	V
	Isolation resistance	DC500V, 40 to 60%RH	R_{ISO}	5×10^{10}	10^{11}		Ω
	Floating capacitance	$V=0, f=1\text{MHz}$	C_f		0.6	1.0	pF
	Cut-off frequency	$V_{CE}=5\text{V}, I_C=2\text{mA}, R_L=100\Omega, -3\text{dB}$	f_c		80		KHz
	Response time	$V_{CE}=2\text{V}, I_C=2\text{mA}, R_L=100\Omega$	t_r		4	18	μs
			t_f		3	18	μs

Notes:

1. Classification table of current transfer ratio is shown below

RANK TABLE OF CURRENT TRANSFER RATIO, CTR

RANK MARK	MIN (%)	MAX (%)
A	80	160
B	130	260
C	200	400
D	300	600

ORDERING INFORMATION				
PART NO. (Note 1&2)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
TPC816x	C9	G	DIP-4	100 / TUBE
TPC816Mx	C9		DIP-4M (Leads with 0.4" spacing)	100 / TUBE
TPC816S1x	RA		SOP-4	2K / 13" Reel

Notes:

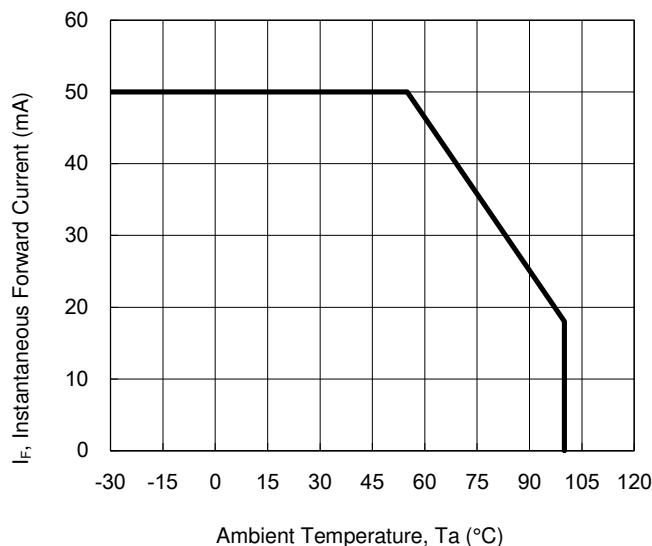
1. "x" defines CTR rank from "A" to "D"
2. Whole series with green compound

EXAMPLE				
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
TPC816A C9G	TPC816A	C9	G	Green compound

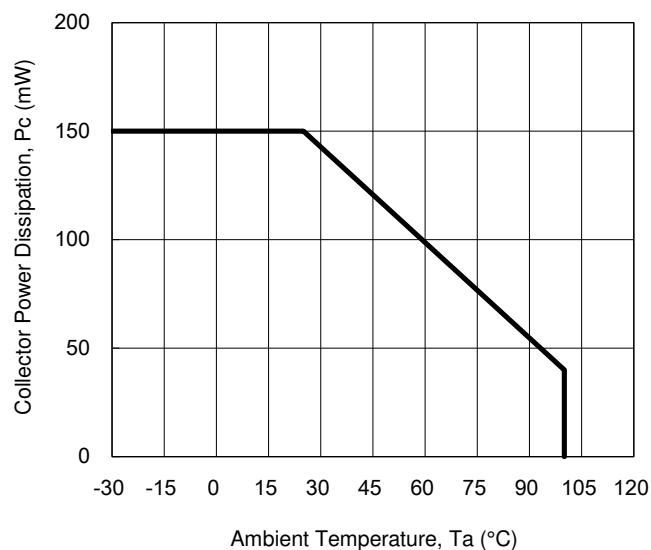
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

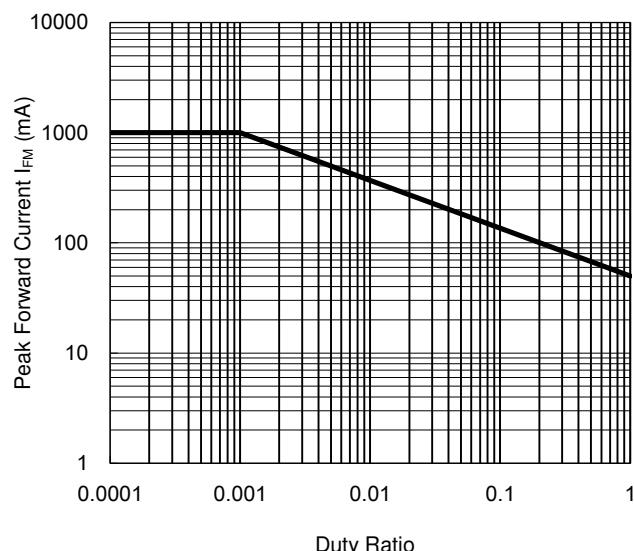
**Fig. 1 Forward Current vs.
Ambient Temperature**



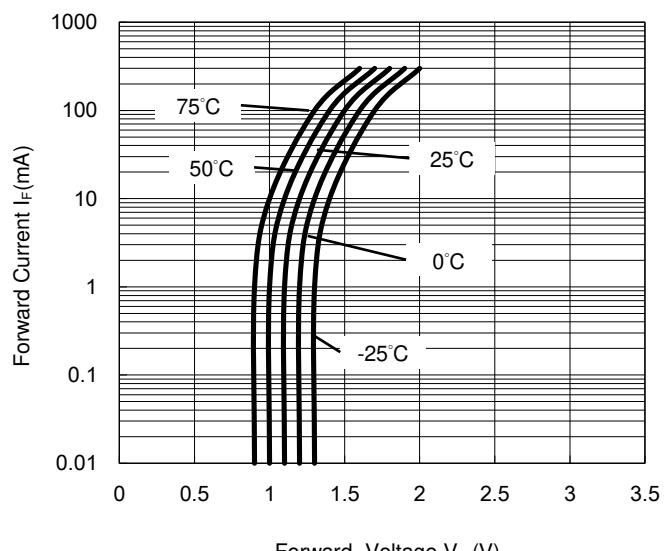
**Fig.2 Collector Power Dissipation vs.
Ambient Temperature**



**Fig.3 Peak Forward Current vs.
Duty Ratio**



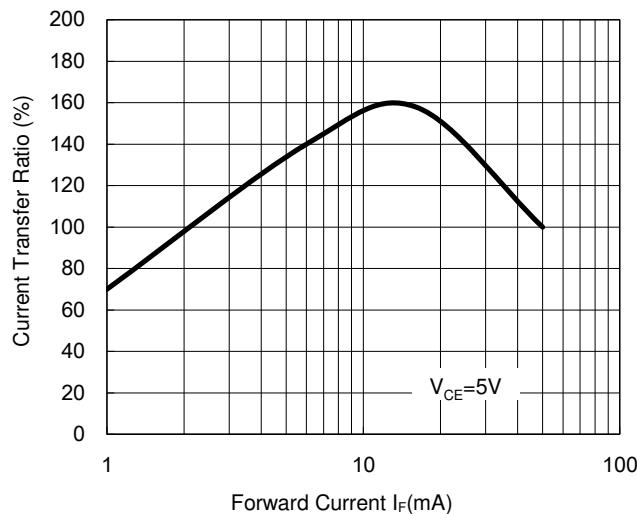
**Fig.4 Forward Current vs.
Forward Voltage**



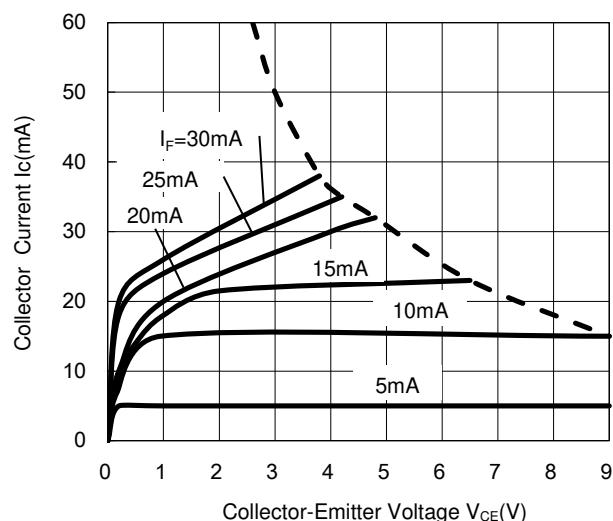
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

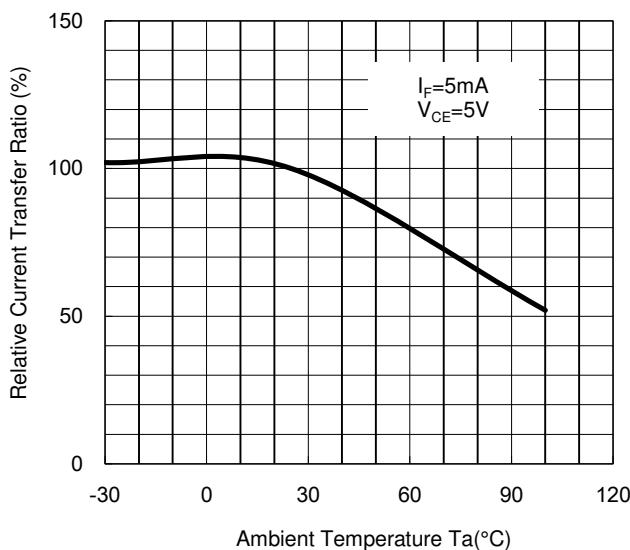
**Fig. 5 Current Transfer Ratio vs.
Forward Current**



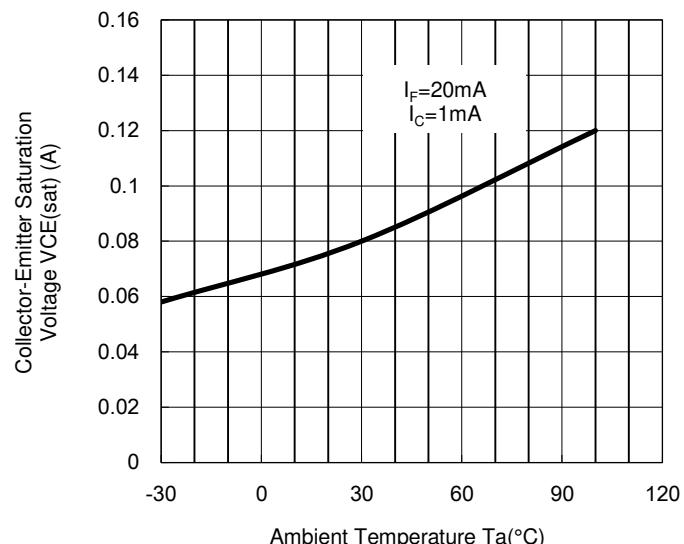
**Fig.6 Collector Current vs.
Collector-Emitter Voltage**



**Fig.7 Relative Current Transfer Ratio vs.
Ambient Temperature**



**Fig.8 Collector-emitter Saturation Voltage vs
Ambient Temperature**



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 9 Collector Dark Current vs.

Ambient Temperature

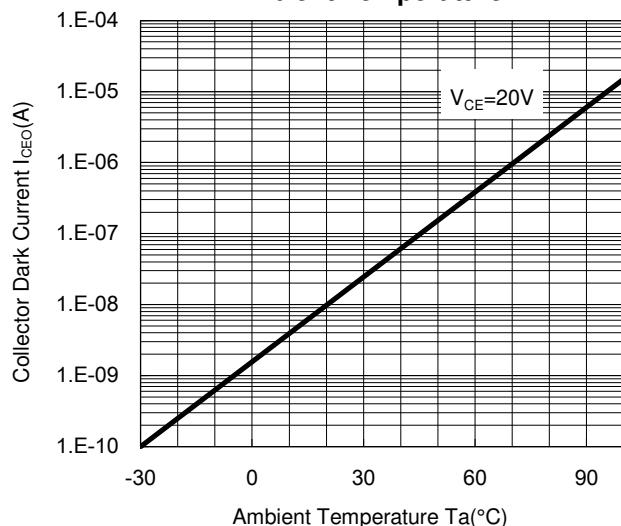


Fig.10 Response Time vs.

Load Resistance

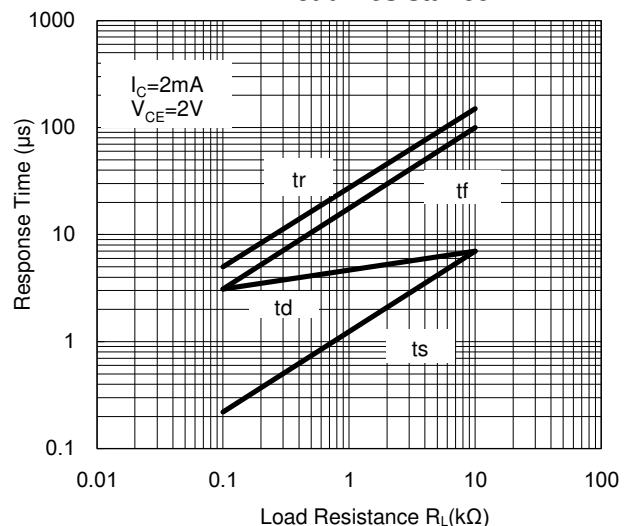


Fig.11 Frequency Response

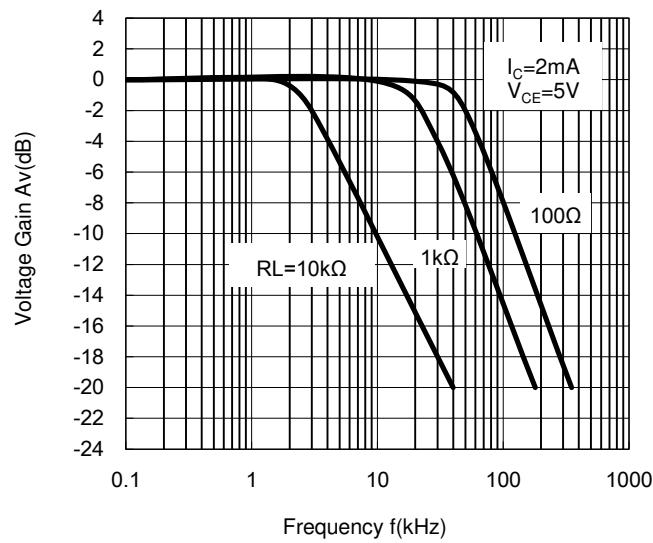
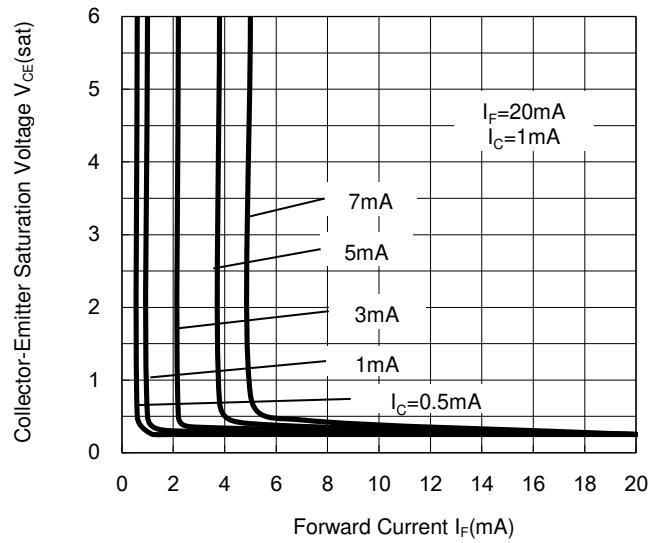
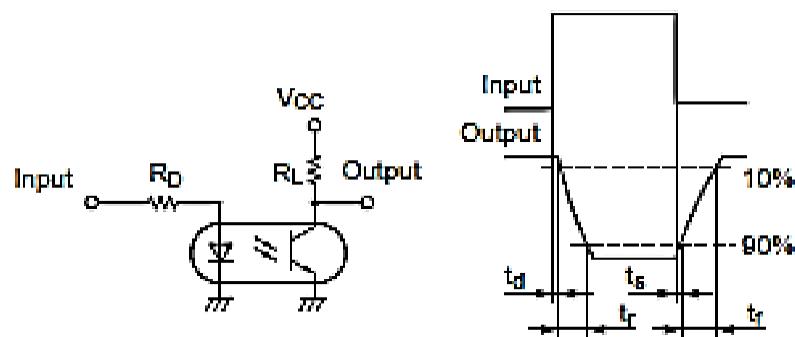


Fig.12 Collector-Emitter Saturation Voltage vs

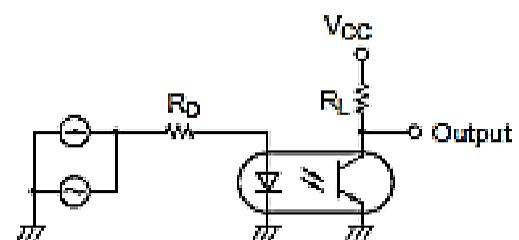
Forward Current

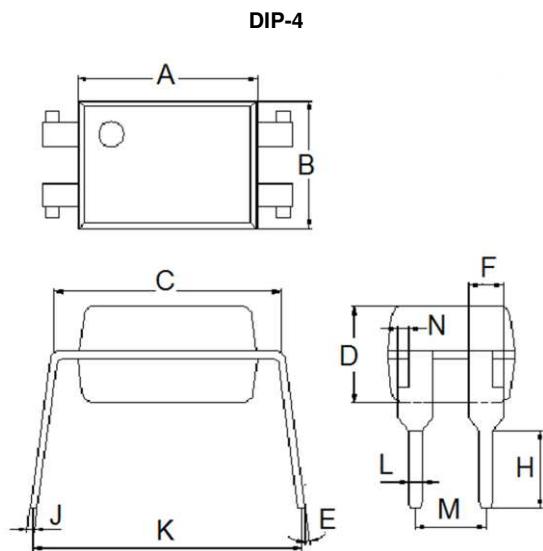


TEST CIRCUIT RESPONSE TIME

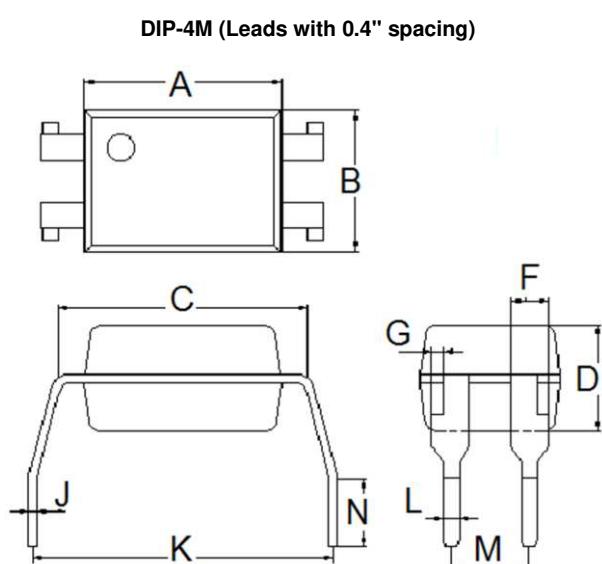


TEST CIRCUIT FOR FREQUENCY RESPONSE

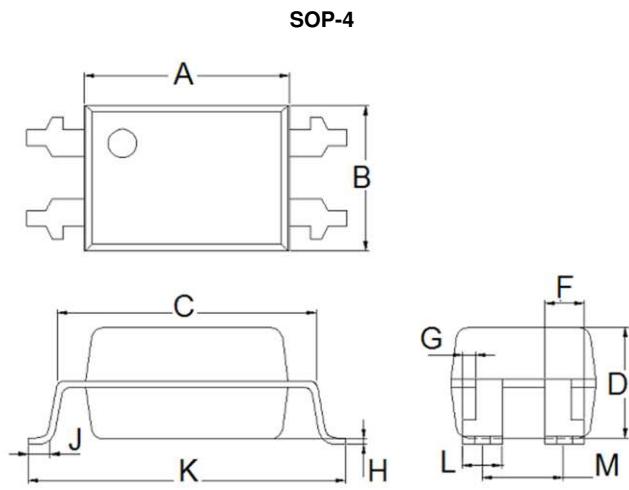


PACKAGE OUTLINE DIMENSION


DIM.	Unit(mm)	
	Min	Max
A	6.40	6.60
B	4.50	4.70
C	7.90	8.30
D	3.28	3.68
E	2°	8°
F	1.25 typ.	
H	2.70	2.90
J	0.23	0.26
K	8.86	9.31
L	0.50 typ.	
M	2.44	2.64
N	0.40 typ.	



DIM.	Unit(mm)	
	Min	Max
A	6.40	6.60
B	4.50	4.70
C	7.90	8.30
D	3.28	3.68
F	1.25 typ.	
G	0.40 typ.	
J	0.23	0.26
K	9.86	10.46
L	0.50 typ.	
M	2.44	2.64
N	2.40	2.90

PACKAGE OUTLINE DIMENSION


DIM.	Unit(mm)	
	Min	Max
A	6.40	6.60
B	4.50	4.70
C	7.90	8.30
D	3.28	3.68
F	1.25 typ.	
G	0.40 typ.	
H	0.00	0.20
J	0.90	1.20
K	9.80	10.30
L	1.25 typ.	
M	2.49	2.69

MARKING

Notes :

- 816: Product type
- B: CTR rank mark
- YWW: Date code

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